

ABSTRACT OF THE DISCLOSURE

A polishing pad and/or platen for use in a chemical mechanical polishing system is provided. The polishing pad and/or platen have slurry distribution/retaining grooves formed on a surface thereof. In one embodiment, the grooves are formed on the upper polishing surface of a pad for use in a rotary or linear polishing system. In another embodiment, an upper mounting surface of a platen is patterned with grooves. The grooves are adapted to direct the flow of slurry inwardly from a perimeter portion of the pad/platen. In operation, the grooves provide uniform distribution of slurry to areas on a polishing pad/platen.

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